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(12) **United States Design Patent**  
**Tauchi et al.**

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(54) **ELECTRODE COVER FOR A PLASMA PROCESSING APPARATUS**

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(51) **LOC (10) Cl.** ..... **13-03**

(52) **U.S. Cl.**  
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(58) **Field of Classification Search**  
USPC ..... D13/158-177, 182, 184; 204/286.1, 204/297.1; 205/118, 123; 200/1 R, 5 R, 52 R, 200/315, 310, 6 A, 302.1, 308, 314, 317, 200/11 R, 16 B  
CPC ..... C25D 17/10; C25D 17/12; C25D 17/14; C25D 17/06; C25D 17/08; C25D 7/12; C25D 7/10; H01L 21/283; H01H 9/02; H01H 9/0214; H01H 9/04; H01H 9/161; H01H 13/04; H01H 13/06; H01H 13/023; H01H 21/08; H01H 19/025  
See application file for complete search history.

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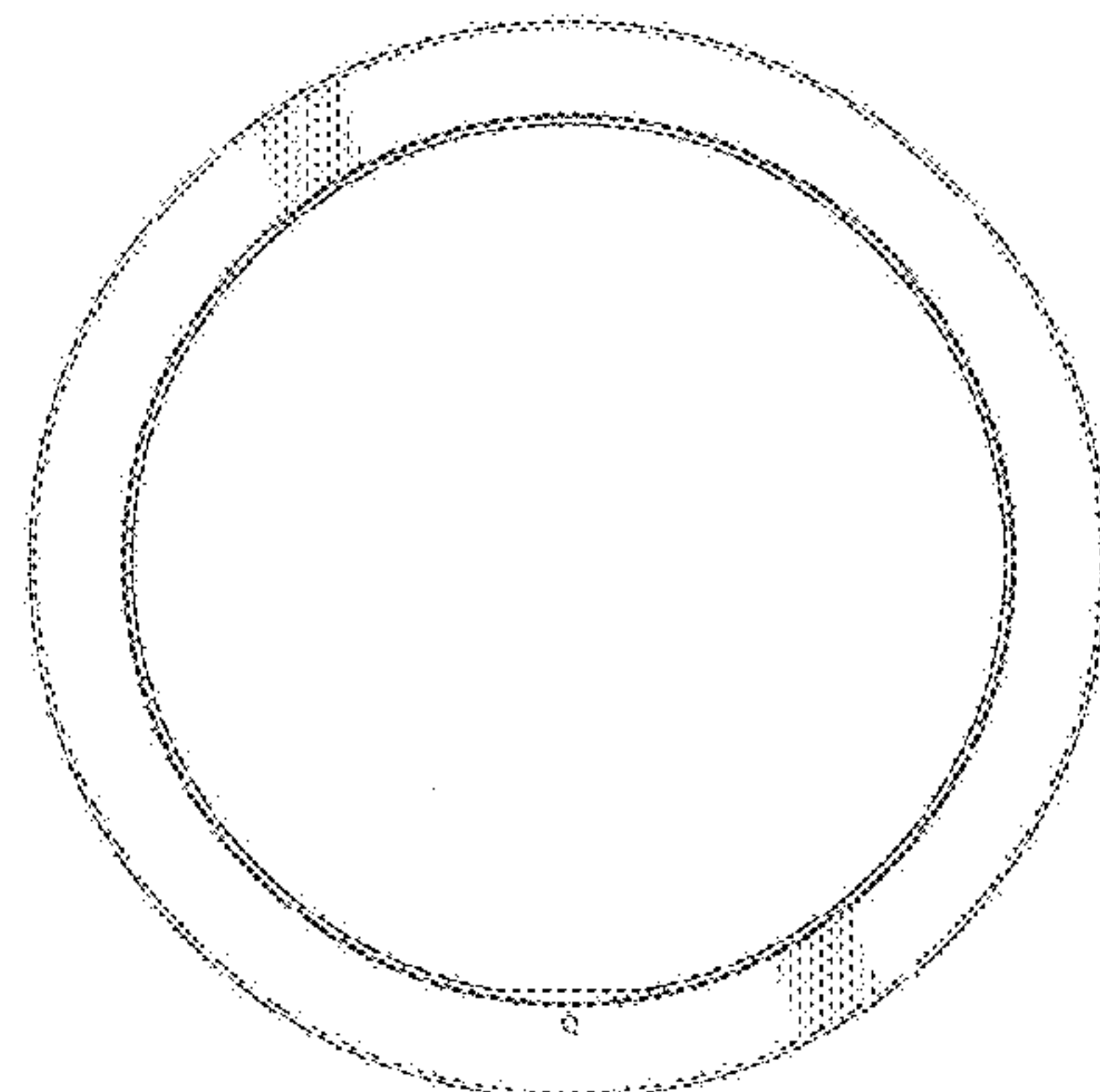
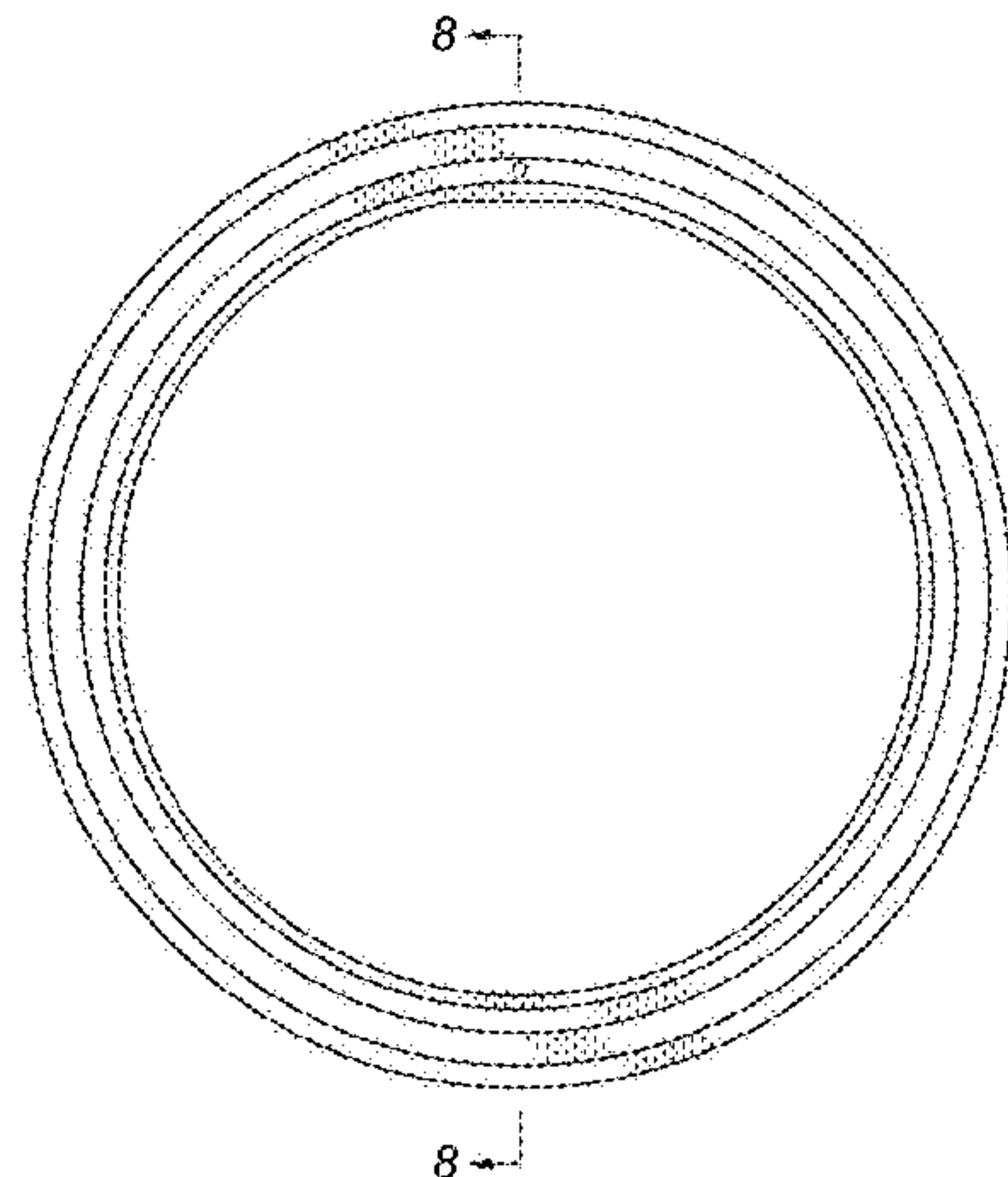
(57) **CLAIM**

The ornamental design for an electrode cover for a plasma processing apparatus, as shown and described.

**DESCRIPTION**

FIG. 1 is a front, top and right side enlarged perspective view of an electrode cover for a plasma processing apparatus showing our new design;  
FIG. 2 is a front elevational view thereof;  
FIG. 3 is a rear elevational view thereof;  
FIG. 4 is a left side elevational view thereof;  
FIG. 5 is a right side elevational view thereof;  
FIG. 6 is a top plan view thereof;  
FIG. 7 is a bottom plan view thereof;  
FIG. 8 is a cross-sectional view taken along line 8-8 of FIG. 6; and,  
FIG. 9 is an enlarged portion view taken along line 9-9 of FIG. 8.

**1 Claim, 5 Drawing Sheets**



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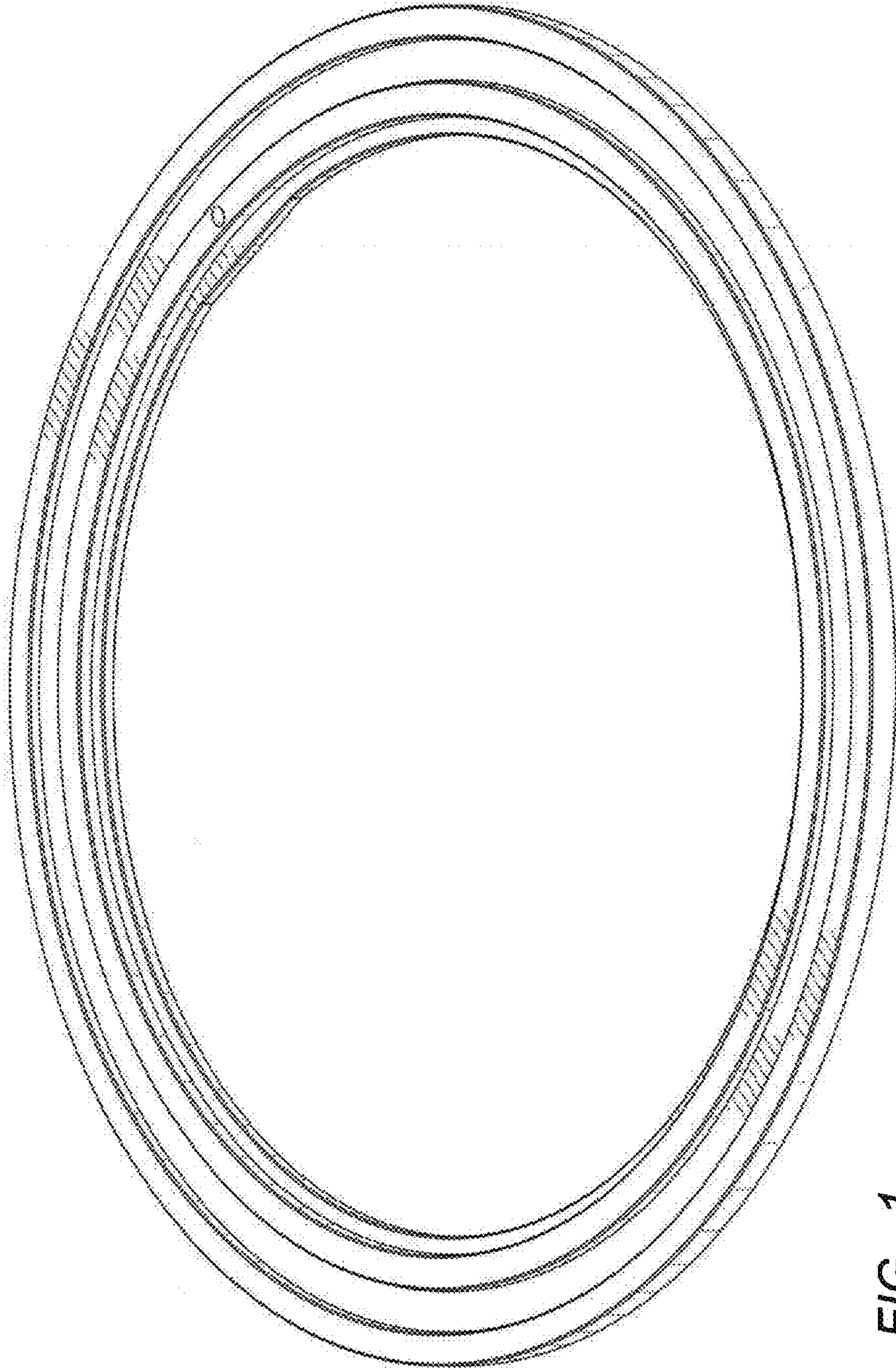
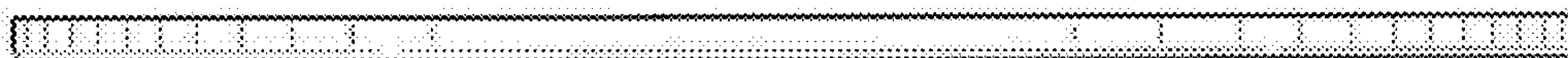
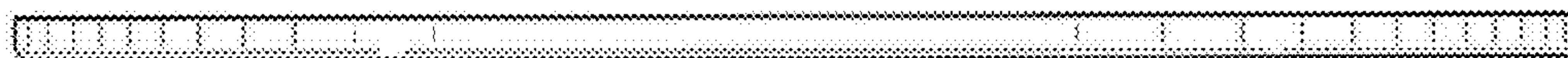


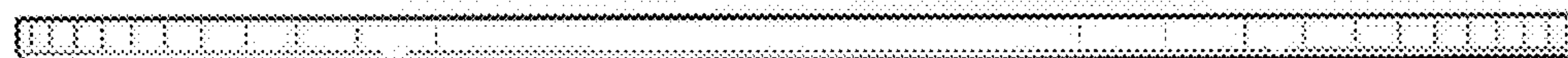
FIG. 1



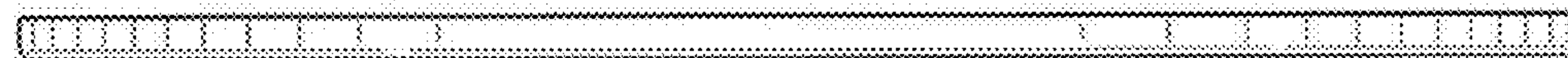
*FIG. 2*



*FIG. 3*



*FIG. 4*



*FIG. 5*



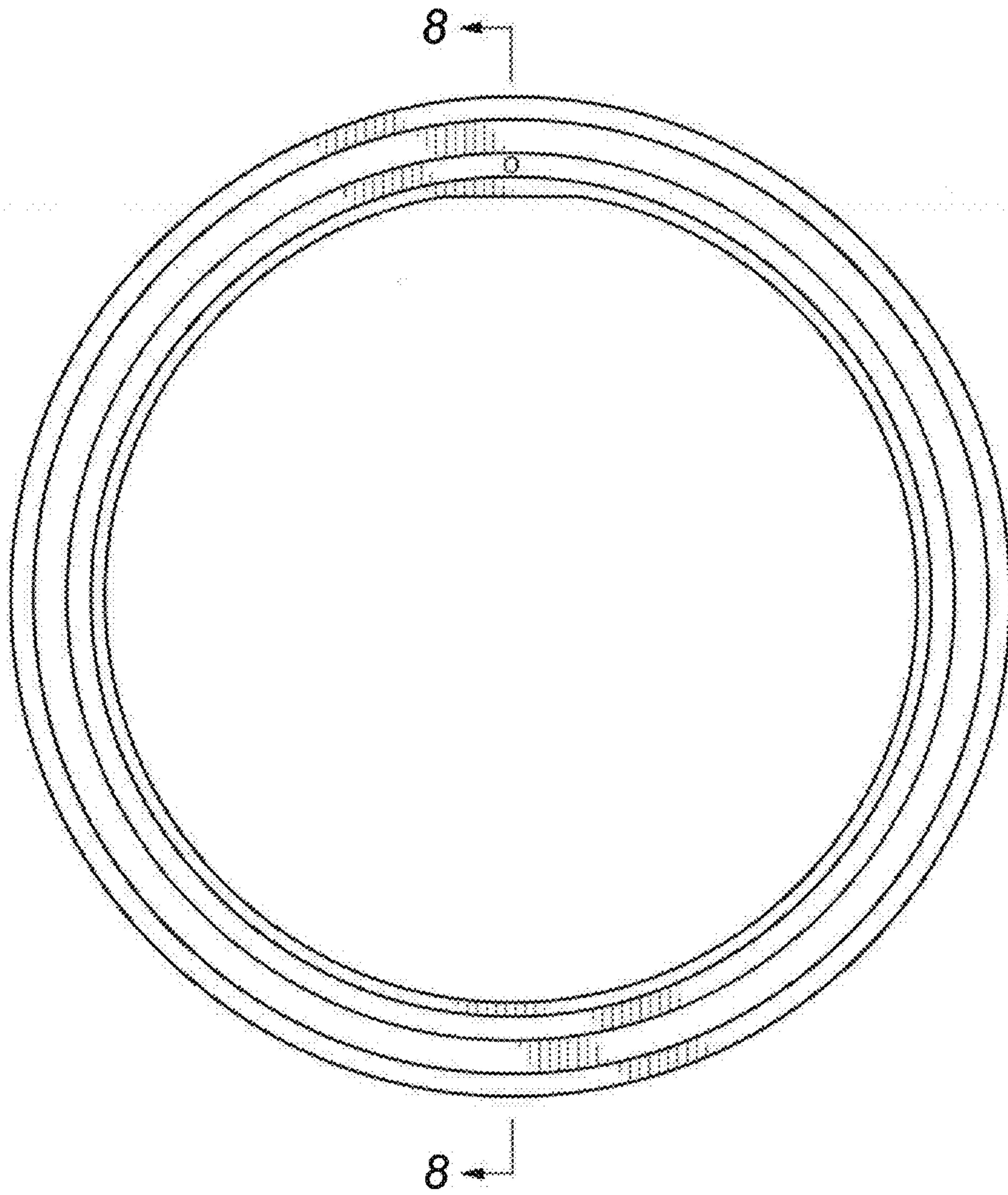


FIG. 6

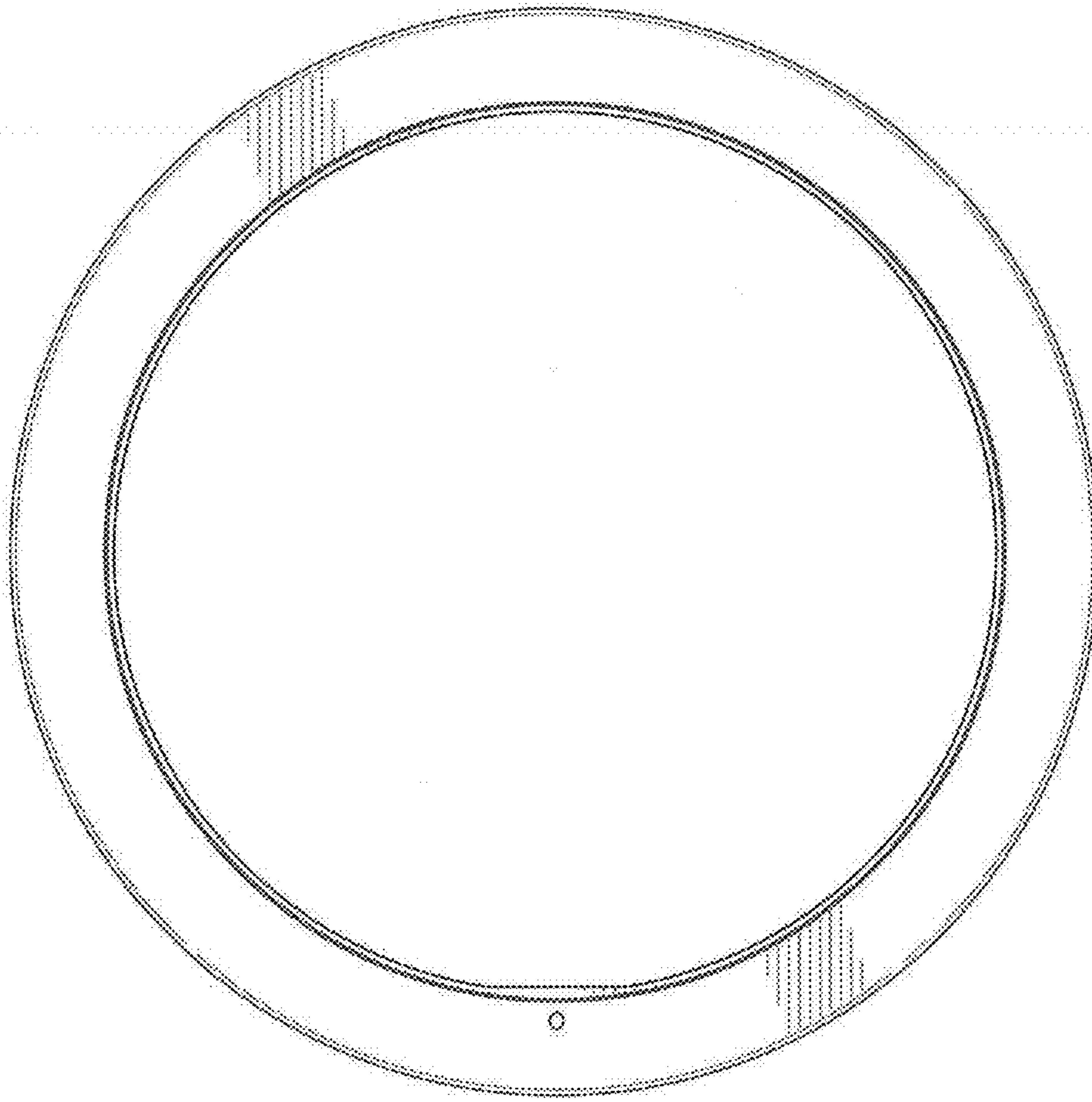


FIG. 7

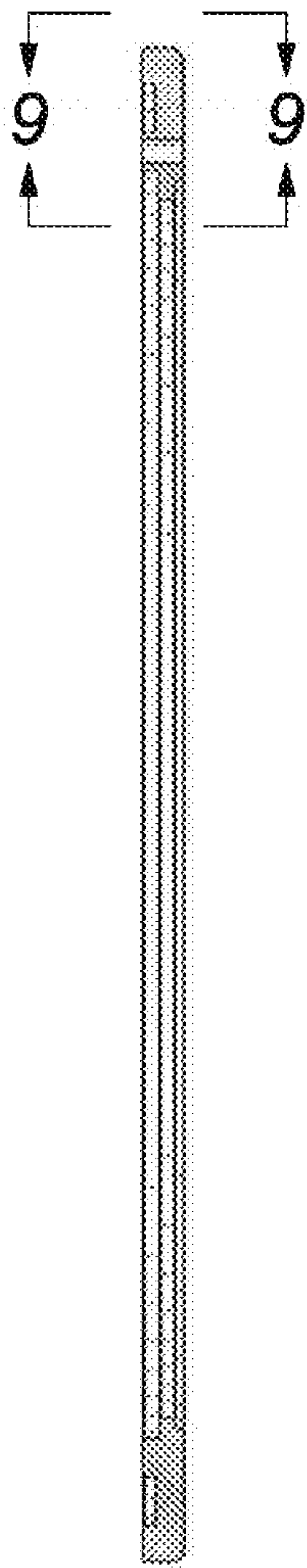


FIG. 8

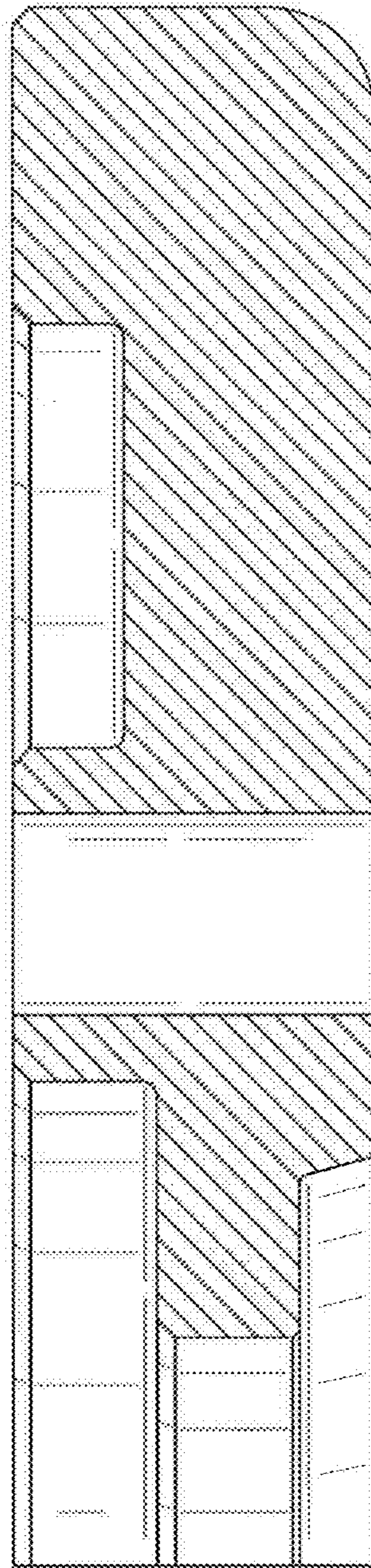


FIG. 9